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(54) **Method and apparatus for treating a waste gas containing fluorine-containing compounds**

(57) The improved apparatus for treatment of a waste gas containing fluorine-containing compounds comprises solids treating means 1 for separating the solids from a waste gas containing fluorine-containing compounds, addition means for adding H₂ and/or H₂O or H₂ and/or H₂O and O₂ as a decomposition assist gas to the waste gas leaving the solids treating means, ther-

mal decomposing means 3 that is packed with γ-alumina 2 heated at 600 - 900°C and which thermally decomposes the waste gas to which the decomposition assist gas has been added, acidic gas treating means 5 for removing acidic gases from the thermally decomposed waste gas, and channels for connecting these means in sequence. The apparatus preferably includes air ejector 7 capable of adjusting its internal pressure.

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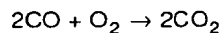
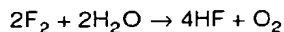
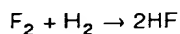
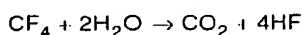
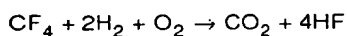
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analyzer for controlling the emission density of the treated gas.

[0014] Fig. 1 is a flowsheet for the waste gas treatment apparatus of the invention.

[0015] The present invention is described below in detail. In the first step, a waste gas containing PFCs, oxidizing gases, acidic gases and CO is passed through a solids treating means such as a water scrubber in order to remove not only the solids such as SiO₂ in the waste gas but also Si compounds such as SiF₄, SiCl₄ and SiBr₄ that may potentially solidify in the thermal decomposing means at the next stage. If the waste gas is directly introduced into the thermal decomposing means without being passed through the solids treating means, clogging or other blocking problems will occur, potentially preventing the waste gas from smoothly flowing through the packed γ-alumina layer. The performance of γ-alumina may also deteriorate. By passing the waste gas through the solids treating means, the solids and the acidic gases containing Si compounds are removed whereas part of oxidizing gases such as F₂, Cl₂ and Br₂ as well as all volumes of PFCs and CO are discharged.

[0016] The waste gas emerging from the solids treating means is then introduced into the thermal decomposing means so that it is decomposed through contact with γ-alumina heated at 500 - 1000°C, preferably 600 - 900°C, more preferably 700 - 900°C. On this occasion, H₂ and/or H₂O; or H₂ and/or H₂O and O₂ are added to the waste gas as a decomposition assist gas so that the components of the waste gas are decomposed into acidic gases and CO₂ according to the following reaction schemes:



[0017] Thus, PFC reacts with H₂ and O₂ or H₂O to be decomposed into CO₂ and HF. Acidic gases such as F₂ react with H₂ or H₂O to be decomposed to another acidic gas HF. Carbon monoxide (CO) is oxidized to CO₂.

[0018] As for PFC, H₂ or H₂O is added in moles at least equal to the moles necessary for the F atoms in the PFC to be converted to HF and O₂ is added in moles at least equal to the moles necessary for the C atoms in the PFC to be converted to CO₂. Preferably, O₂ is added in moles which are at least equal to the sum of

one mole and the above-defined minimum number of moles. As for oxidizing gases, H₂ is introduced in moles at least equal to the moles necessary for the halogen atoms (X) in the oxidizing gas to be converted to an acidic gas (HX).

[0019] The waste gas leaving the thermal decomposing means only contains the acidic gases (HX) and CO₂ and by subsequent treatment with an acidic gas treating means such as a water scrubber, the acidic gases are completely removed.

[0020] The alumina to be used in the invention may have a γ-crystalline structure without a uniform pore distribution. While the shape of the alumina is not limited in any particular way, spheres are easy to handle and, hence, preferred. To the extent that will not unduly increase the resistance to the passage of the waste gas, the particle size of γ-alumina should be as small as possible, preferably between 0.8 mm and 2.6 mm. The γ-alumina may be held at between 500°C and 1000°C, preferably 600°C and 900°C and more preferably 700°C and 900°C during the passage of the waste gas.

[0021] The solids treating means and the acidic gas treating means are preferably a packed column or a spray column on the condition that they are adapted to spray water. The thermal decomposing means should be adapted to permit the introduction of H₂ and/or H₂O or H₂ and/or H₂O and O₂ as a decomposition assist gas.

[0022] Fig. 1 is a flowsheet for the waste gas treatment apparatus of the invention. It generally comprises the solids treating means 1, the γ-alumina packed layer 2, the thermal decomposing means 3, a cleaning water circulating pump 4, the acidic gas treating means 5, an FT-IR analyzer 6, an air ejector 7 and a bypass valve 8.

[0023] A waste gas 9 containing PFCs, oxidizing gases, acidic gases and CO is first passed through the spray column (solids treating means) 1 so as to remove the solids and Si compounds. The waste gas is then passed through the thermal decomposing means 3 which is also supplied with H₂, O₂ and H₂O to decompose the PFCs, oxidizing gases and CO into acidic gases and CO₂. The acidic gases are removed by passage through the next spray column (acidic gas treating means) 5, from which the treated gas 10 emerges.

[0024] The air ejector 7 is installed to control the pressure in each of the treating means and the FT-IR analyzer 6 is provided to monitor the treated gas.

[0025] Spray water 11 is introduced into the acidic gas treating means 5 and the spent water is forced to the solids treating means 1 with the cleaning water circulating pump 4; the water is used in spraying there and discharged as wastewater 12.

[0026] The following examples are provided for the purpose of further illustrating the present invention but are in no way to be taken as limiting.

Example 1

[0027] A quartz column of 25 mmφ was packed with

remove solids before the thermal decomposing step

ejector

been reduced to below the detection limit (2 ppm) after the passage of the feed gas for 3 hours. Obviously, CO was oxidized to CO₂ by addition of O₂.

Example 3

[0040] An experiment was conducted using the same equipment as in Example 1 that was packed with the same γ -alumina in the same amount and heated to 700°C. The total gas flow rate was 408 sccm; in addition to N₂-diluted CF₄, H₂O was supplied at a rate of 0.040 mL/min which was 14 times as much as CF₄ and O₂ was supplied in moles at least equal to the moles necessary for the C atom in CF₄ to be converted to CO₂; the entrance concentrations of CF₄ and O₂ were 0.89% and 3.0%, respectively.

[0041] As it turned out, the removal of CF₄ dropped below 98% when the passage of the feed gas continued for 23 hours. At this point in time, the throughput was 110 L/L, which was 1.4 times higher than the throughput of CF₄ treatment in the presence of added H₂ and O₂. Throughout the experiment, the concentration of CO was below the tolerable level.

Comparative Example 3

[0042] In order to evaluate the effectiveness of the wet process in treating oxidizing gases and acidic gases, a water cleaning column (210 mm ϕ x 430 mm^H with a Raschig ring packed to a height of 170 mm) was supplied with a waste gas at a total rate of 60 L/min and spray water at a rate of 3.5 L/min. The waste gas was prepared from F₂, SiF₄ and Cl₂ which had entrance concentrations of 1100 ppm, 1600 ppm and 5100 ppm, respectively. At the exit of the column, F₂, SiF₄ and Cl₂ were detected at concentrations of 11 ppm, < 1 ppm, and 3300 ppm, respectively. Obviously, SiF₄ was effectively treated but F₂ and Cl₂ leaked out.

Example 4

[0043] A water cleaning column (210 mm ϕ x 430 mm^H with a Raschig ring packed to a height of 170 mm) was used as a solids treating means. This column was combined with a thermal decomposing means comprising a preheating chamber and a catalyst packed chamber and an acidic gas treating means which was the same as the water cleaning column. The exit gas leaving the acidic gas treating means was monitored with an FT-IR analyzer (Infinity 6000 of MATTSON) and the pressure in the experimental system was controlled with an air ejector of Daito Seisakusho K.K. The solids treating means and the acidic gas treating means were supplied with cleaning water at respective flow rates of 2 L/min and 4 L/min. The thermal decomposing means was supplied with air and pure water at respective flow rates of 10 L/min and 2.4 mL/min. The catalyst was 15 L of γ -alumina (NEOBEAD GB-08 of Mizusawa Kagaku K.K.)

[0044] A gas dryer (MD-70-72P of PERMAPUR) was installed ahead of the FT-IR analyzer for removing the moisture in the waste gas. Air was supplied into the air ejector at a rate of 30 L/min so that the pressure in the system was kept at a negative value of -0.5 kPa. A waste gas was introduced at a flow rate of 60 L/min and it was prepared from a N₂ base containing CF₄, SiF₄, F₂ and CO at respective concentrations of 0.5%, 0.3%, 0.3% and 0.3%. The waste gas was first passed through the solids treating means, then passed through the thermal decomposing means in the presence of added water and O₂, with the catalyst bed being heated at 700°C. The waste gas was subsequently passed through the acidic gas treating means and the treated gas was continuously analyzed by FT-IR. After the passage of the waste gas for 10 hours, CO₂ was detected in an amount of 6900 ppm but each of CF₄, SiF₄, HF and CO had been treated to below 1 ppm. No F₂ was detected by ion chromatographic analysis.

Example 5

[0045] A waste gas treatment was conducted with the same experimental setup under the same conditions as in Example 4, except that CF₄ was replaced by C₂F₆ and that the waste gas was prepared from a N₂ base containing C₂F₆, SiF₄, F₂ and CO at respective concentrations of 0.5%, 0.3%, 0.3% and 0.3%. The waste gas was passed through the solids treating means, the thermal decomposing means and the acidic gas treating means.

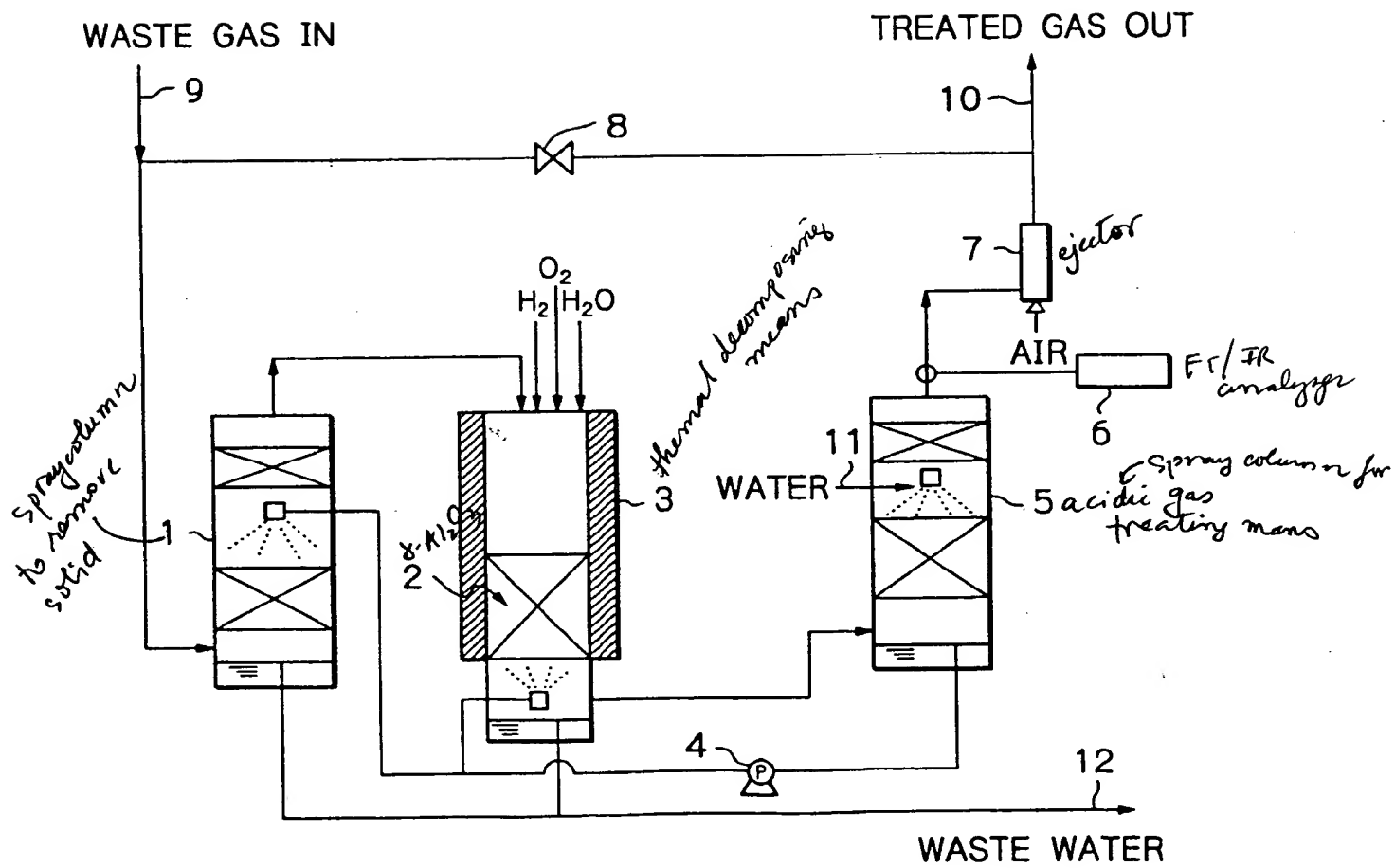
[0046] The treated gas emerging from the acidic gas treating means was continuously analyzed by FT-IR. After the passage of the waste gas for 10 hours, CO₂ was detected in an amount of 11000 ppm but each of C₂F₆, SiF₄, HF and CO had been treated to below 1 ppm. No F₂ was detected by ion chromatographic analysis.

[0047] According to the invention, harmful waste gases from the semiconductor fabrication process that contain PFCs, oxidizing gases, acidic gases and CO and which are a potential accelerator of global warming can be treated in such a way that high percent decomposition is maintained for a prolonged time.

Claims

1. A method for treatment of a waste gas containing fluorine-containing compounds which comprises the steps of separating the solids from the waste gas, adding H₂ and/or H₂O or H₂ and/or H₂O and O₂ as a decomposition assist gas, thermally decomposing the waste gas by contact with γ -alumina at 500 - 1000°C, and removing acidic gases from the decomposed waste gas.
2. The method according to claim 1, wherein the temperature used in the thermally decomposing step

Fig. 1



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**ANNEX TO THE EUROPEAN SEARCH REPORT
ON EUROPEAN PATENT APPLICATION NO.**

EP 00 12 5010

This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report.
The members are as contained in the European Patent Office EDP file on
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